

Title (en)  
METHOD FOR PRODUCTION OF PIECES FOR PASSIVE ELECTRONIC COMPONENTS

Title (de)  
VERFAHREN ZUR HERSTELLUNG DER BAUTEILE FÜR PASSIVE ELEKTRONISCHE BAUELEMENTE

Title (fr)  
PROCEDE DE FABRICATION DE PIECES POUR COMPOSANTS ELECTRONIQUES PASSIFS

Publication  
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Application  
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Abstract (en)  
[origin: WO2005002308A2] The invention relates to a method for production of pieces for passive electronic components in which: a layered strip (1) is produced, made from at least one stack of a thin metal strip and a layer of adhesive material, at least one piece (6) is cut from the layered strip (1), the cutting being carried out by a method including at least one etching step with sand. The invention further relates to the pieces obtained.

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IPC 8 full level  
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See references of WO 2005002308A2

Citation (examination)  
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JP 2009224800 A 20091001; JP 4381414 B2 20091209; JP 4917632 B2 20120418; KR 101104385 B1 20120116; KR 20060017651 A 20060224;  
US 2007119284 A1 20070531; US 2009314521 A1 20091224; US 7640641 B2 20100105; US 8362361 B2 20130129;  
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